

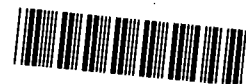
AbstractMethod and Device for wire bonding

The present invention relates to a device for wire bonding comprising a guidance for a bond wire and a melt inducing device for melting the surface of a definite region of the bond wire surface, whereby the bond wire guidance is adapted to guide the definite region of the bond wire into a bonding area (1) and connect it to at least one bond pad, whereby the bonding area (1) comprises a process gas inlet (3), characterized in that the process gas inlet (3) is connected to an on-site gas generator (5) which generates the process gas. In addition, the present invention relates to a method for wire bonding comprising the steps of: connecting a definite region of a guided bond wire to a bond pad, whereby the surface of the definite region is previously melted and the whole process takes place within a bonding area (1), which contains a process gas, which is led into the bonding area prior or during the bonding process, characterized in that at least a part of the process gas is generated by an on-site gas generator (5).

(Fig. 2)



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